

3.3V ZERO DELAY CLOCK BUFFER, SPREAD SPECTRUM COMPATIBLE

FEATURES:

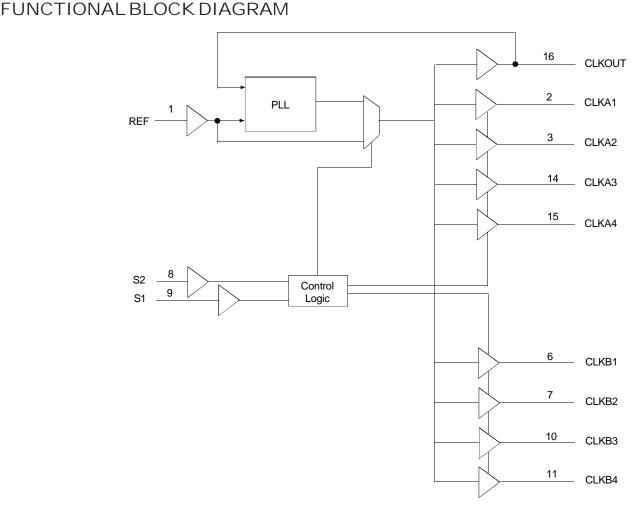
- Phase-Lock Loop Clock Distribution
- 10MHz to 200MHz operating frequency
- Distributes one clock input to one bank of five and one bank of four outputs
- · Separate output enable for each output bank
- Output Skew < 250ps
- Low jitter <200 ps cycle-to-cycle
- IDT23S09E-1 for Standard Drive
- IDT23S09E-1H for High Drive
- · No external RC network required
- Operates at 3.3V VDD
- Spread spectrum compatible
- Available in SOIC and TSSOP packages

DESCRIPTION:

The IDT23S09E is a high-speed phase-lock loop (PLL) clock buffer, designed to address high-speed clock distribution applications. The zero delay is achieved by aligning the phase between the incoming clock and the output clock, operable within the range of 10 to 200MHz.

The IDT23S09E is a 16-pin version of the IDT23S05E. The IDT23S09E accepts one reference input, and drives two banks of four low skew clocks. The -1H version of this device operates up to 200MHz frequency and has higher drive than the -1 device. All parts have on-chip PLLs which lock to an input clock on the REF pin. The PLL feedback is on-chip and is obtained from the CLKOUT pad. In the absence of an input clock, the IDT23S09E enters power down. In this mode, the device will draw less than 12µA for Commercial Temperature range and less than 25µA for Industrial temperature range, and the outputs are tri-stated.

The IDT23S09E is characterized for both Industrial and Commercial operation.



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COMMERCIAL AND INDUSTRIAL TEMPERATURE RANGES

OCTOBER 2003

IDT23S09E 3.3VZERO DELAY CLOCK BUFFER

COMMERCIAL AND INDUSTRIAL TEMPERATURE RANGES

Unit

V

V

V

mΑ

mΑ

mΑ

W

°C

°C

°C

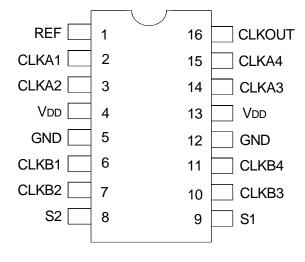
0.7

-65 to +150

0 to +70

-40 to +85

PINCONFIGURATION



SOIC/ TSSOP TOP VIEW

APPLICATIONS:

- SDRAM
- Telecom
- Datacom
- PC Motherboards/Workstations
- Critical Path Delay Designs

PIN DESCRIPTION

Symbol Rating Max. -0.5 to +4.6 Vdd Supply Voltage Range VI⁽²⁾ Input Voltage Range (REF) -0.5 to +5.5 Vi Input Voltage Range -0.5 to VDD+0.5 (except REF) IIK (VI < 0) Input Clamp Current -50 Io (Vo = 0 to VDD) Continuous Output Current ±50 VDD or GND Continuous Current ±100

Maximum Power Dissipation

Storage Temperature Range

Commercial Temperature

Industrial Temperature

Range

Range

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Temperature
NOTES:

 $TA = 55^{\circ}C$

(in still air)(3)

Operating

Operating

Temperature

Tstg

 Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

 The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

Pin Name	Pin Number	Туре	Functional Description	
REF ⁽¹⁾	1	IN	Input reference clock, 5 Volt tolerant input	
CLKA1 ⁽²⁾	2	Out	Output clock for bank A	
CLKA2 ⁽²⁾	3	Out	Output clock for bank A	
Vdd	4, 13	PWR	3.3V Supply	
GND	5,12	GND	Ground	
CLKB1 ⁽²⁾	6	Out	Output clock for bank B	
CLKB2 ⁽²⁾	7	Out	Output clock for bank B	
S2 ⁽³⁾	8	IN	Select input Bit 2	
S1 ⁽³⁾	9	IN	Select input Bit 1	
CLKB3 ⁽²⁾	10	Out	Output clock for bank B	
CLKB4 ⁽²⁾	11	Out	Output clock for bank B	
CLKA3 ⁽²⁾	14	Out	Output clock for bank A	
CLKA4 ⁽²⁾	15	Out	Output clock for bank A	
CLKOUT ⁽²⁾	16	Out	Output clock, internal feedback on this pin	

NOTES:

1. Weak pull down.

2. Weak pull down on all outputs.

3. Weak pull ups on these inputs.

FUNCTION TABLE⁽¹⁾

S2	S1	CLKA	CLKB	CLKOUT ⁽²⁾	Output Source	PLL Shut Down
L	L	Tri-State	Tri-State	Driven	PLL	Ν
L	Н	Driven	Tri-State	Driven	PLL	Ν
Н	L	Driven	Driven	Driven	REF	Y
Н	Н	Driven	Driven	Driven	PLL	Ν

NOTES:

1. H = HIGH Voltage Level.

L = LOW Voltage Level

2. This output is driven and has an internal feedback for the PLL. The load on this ouput can be adjusted to change the skew between the REF and the output.

DC ELECTRICAL CHARACTERISTICS - COMMERCIAL

Symbol	Parameter	Co	Conditions		Max.	Unit
Vil	Input LOW Voltage Level			-	0.8	V
Vih	Input HIGH Voltage Level			2	_	V
lil	Input LOW Current	VIN = OV		-	50	μA
Ін	Input HIGH Current	VIN = VDD	Vin = Vdd		100	μA
Vol	Output LOW Voltage	Standard Drive	Iol = 8mA	-	0.4	V
		High Drive	IoL = 12mA (-1H)			
Vон	Output HIGH Voltage	Standard Drive	Iон = -8mA	2.4	_	V
		High Drive	Іон = -12mA (-1H)			
IDD_PD	Power Down Current	REF = 0MHz (S2 = S1 =	= H)	_	12	μA
Idd	Supply Current	Unloaded Outputs at 66.0	66MHz, SEL inputs at VDD or GND	_	32	mA

OPERATING CONDITIONS - COMMERCIAL

Symbol	Parameter	Min.	Max.	Unit
Vdd	Supply Voltage	3	3.6	V
TA	Operating Temperature (Ambient Temperature)	0	70	°C
Cl	Load Capacitance < 100MHz	—	30	pF
	Load Capacitance 100MHz - 200MHz	_	10	
Cin	Input Capacitance	_	7	pF

SWITCHING CHARACTERISTICS (23S09E-1) - COMMERCIAL^(1,2)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
tı	Output Frequency	10pF Load	10	_	200	MHz
		30pF Load	10	—	100	
	Duty Cycle = $t_2 \div t_1$	Measured at 1.4V, FOUT = 66.66MHz	40	50	60	%
t3	RiseTime	Measured between 0.8V and 2V	—	—	2.5	ns
t4	Fall Time	Measured between 0.8V and 2V	_	—	2.5	ns
ts	Output to Output Skew	All outputs equally loaded	_	—	250	ps
t6A	Delay, REF Rising Edge to CLKOUT Rising Edge ⁽²⁾	Measured at VDD/2	—	0	±350	ps
t6B	Delay, REF Rising Edge to CLKOUT Rising Edge ⁽²⁾	Measured at VDD/2 in PLL bypass mode (IDT23S09E only)	1	5	8.7	ns
tz	Device-to-Device Skew	Measured at VDD/2 on the CLKOUT pins of devices	_	0	700	ps
tı	Cycle-to-Cycle Jitter	Measured at 66.66MHz, loaded outputs	_	_	200	ps
tlock	PLL Lock Time	Stable power supply, valid clock presented on REF pin		_	1	ms

NOTES:

1. REF Input has a threshold voltage of VDD/2.

2. All parameters specified with loaded outputs.

SWITCHING CHARACTERISTICS (23S09E-1H) - COMMERCIAL^(1,2)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
tı	Output Frequency	10pF Load	10	—	200	MHz
		30pF Load	10	—	100	
	Duty Cycle = $t_2 \div t_1$	Measured at 1.4V, FOUT = 66.66MHz	40	50	60	%
	Duty Cycle = $t_2 \div t_1$	Measured at 1.4V, Fout <50MHz	45	50	55	%
ß	RiseTime	Measured between 0.8V and 2V	—	—	1.5	ns
t4	FallTime	Measured between 0.8V and 2V	—	—	1.5	ns
ts	Output to Output Skew	All outputs equally loaded	—	—	250	ps
t6A	Delay, REF Rising Edge to CLKOUT Rising Edge	Measured at VDD/2	_	0	±350	ps
t6B	Delay, REF Rising Edge to CLKOUT Rising Edge	Measured at VDD/2 in PLL bypass mode (IDT23S09E only)	1	5	8.7	ns
ħ	Device-to-Device Skew	Measured at VDD/2 on the CLKOUT pins of devices	—	0	700	ps
t8	Output Slew Rate	Measured between 0.8V and 2V using Test Circuit 2	1	—	_	V/ns
t	Cycle-to-Cycle Jitter	Measured at 66.66MHz, loaded outputs		_	200	ps
t LOCK	PLL Lock Time	Stable power supply, valid clock presented on REF pin	_	_	1	ms

NOTES:

REF Input has a threshold voltage of VDD/2.
All parameters specified with loaded outputs.

DC ELECTRICAL CHARACTERISTICS - INDUSTRIAL

Symbol	Parameter	C	Conditions		Max.	Unit
Vil	Input LOW Voltage Level			—	0.8	V
Vih	Input HIGH Voltage Level			2	_	V
lil	Input LOW Current	VIN = 0V		—	50	μA
Ін	Input HIGH Current	VIN = VDD		—	100	μA
Vol	Output LOW Voltage	Standard Drive	Iol = 8mA	-	0.4	V
		High Drive	IoL = 12mA (-1H)			
Vон	Output HIGH Voltage	Standard Drive	юн = -8mA	2.4	_	V
		High Drive	Іон = -12mA (-1H)			
IDD_PD	Power Down Current	REF = 0MHz (S2 = S1	= H)	—	25	μA
DD	Supply Current	Unloaded Outputs at 66.	66MHz, SEL inputs at VDD or GND	-	35	mA

OPERATING CONDITIONS - INDUSTRIAL

Symbol	Parameter	Min.	Max.	Unit
Vdd	SupplyVoltage	3	3.6	V
TA	Operating Temperature (Ambient Temperature)	-40	+85	°C
CL	Load Capacitance < 100MHz	—	30	pF
	Load Capacitance 100MHz - 200MHz	_	10	
Cin	InputCapacitance	_	7	pF

SWITCHING CHARACTERISTICS (23S09E-1) - INDUSTRIAL^(1,2)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
tı	Output Frequency	10pF Load	10	—	200	MHz
		30pF Load	10	—	100	
	Duty Cycle = t2 ÷ t1	Measured at 1.4V, FOUT = 66.66MHz	40	50	60	%
t3	RiseTime	Measured between 0.8V and 2V	_	—	2.5	ns
t4	FallTime	Measured between 0.8V and 2V	—	—	2.5	ns
t5	Output to Output Skew	All outputs equally loaded	_	—	250	ps
t6A	Delay, REF Rising Edge to CLKOUT Rising Edge	Measured at VDD/2	_	0	±350	ps
t6B	Delay, REF Rising Edge to CLKOUT Rising Edge	Measured at VDD/2 in PLL bypass mode (IDT23S09E only)	1	5	8.7	ns
t	Device-to-Device Skew	Measured at VDD/2 on the CLKOUT pins of devices	_	0	700	ps
tı	Cycle-to-Cycle Jitter	Measured at 66.66MHz, loaded outputs	_	_	200	ps
tlock	PLL Lock Time	Stable power supply, valid clock presented on REF pin	_	_	1	ms

NOTES:

1. REF Input has a threshold voltage of VDD/2.

2. All parameters specified with loaded outputs.

SWITCHING CHARACTERISTICS (23S09E-1H) - INDUSTRIAL^(1,2)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
tı	Output Frequency	10pF Load	10	_	200	MHz
		30pF Load	10	—	100	
	Duty Cycle = $t_2 \div t_1$	Measured at 1.4V, FOUT = 66.66MHz	40	50	60	%
	Duty Cycle = $t_2 \div t_1$	Measured at 1.4V, Fout <50MHz	45	50	55	%
t3	RiseTime	Measured between 0.8V and 2V	—	-	1.5	ns
t4	FallTime	Measured between 0.8V and 2V	—	_	1.5	ns
ts	Output to Output Skew	All outputs equally loaded	—	_	250	ps
t6A	Delay, REF Rising Edge to CLKOUT Rising Edge	Measured at VDD/2	—	0	±350	ps
t6B	Delay, REF Rising Edge to CLKOUT Rising Edge	Measured at VDD/2 in PLL bypass mode (IDT23S09E only)	1	5	8.7	ns
t	Device-to-Device Skew	Measured at VDD/2 on the CLKOUT pins of devices	—	0	700	ps
t8	Output Slew Rate	Measured between 0.8V and 2V using Test Circuit 2	1	_	_	V/ns
tı	Cycle-to-Cycle Jitter	Measured at 66.66MHz, loaded outputs		_	200	ps
tlocк	PLL Lock Time	Stable power supply, valid clock presented on REF pin	_	_	1	ms

NOTES:

1. REF Input has a threshold voltage of VDD/2.

2. All parameters specified with loaded outputs.

ZERO DELAY AND SKEW CONTROL

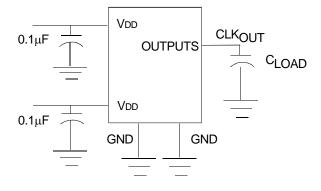
All outputs should be uniformly loaded in order to achieve Zero I/O Delay. Since the CLKOUT pin is the internal feedback for the PLL, its relative loading can affect and adjust the input/output delay.

For designs utilizing zero I/O Delay, all outputs including CLKOUT must be equally loaded. Even if the output is not used, it must have a capacitive load equal to that on the other outputs in order to obtain true zero I/O Delay. For zero output-to-output skew, all outputs must be loaded equally.

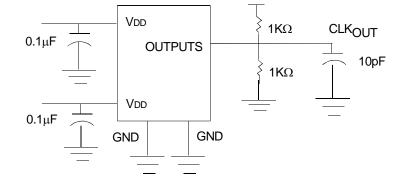
SPREAD SPECTRUM COMPATIBLE

Many systems being designed now use a technology called Spread Spectrum Frequency Timing Generation. This product is designed not to filter off the Spread Spectrum feature of the reference input, assuming it exists. When a zero delay buffer is not designed to pass the Spread Spectrum feature through, the result is a significant amount of tracking skew, which may cause problems in systems requiring synchronization.

TESTCIRCUITS

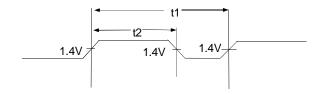




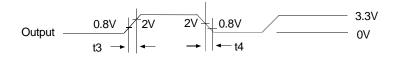


Test Circuit 2 (t8, Output Slew Rate On -1H Devices)

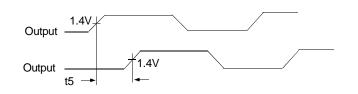
SWITCHING WAVEFORMS



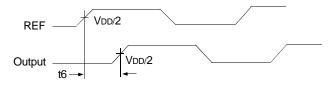
Duty Cycle Timing



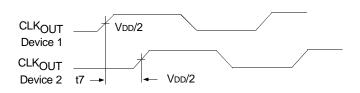
All Outputs Rise/Fall Time



Output to Output Skew

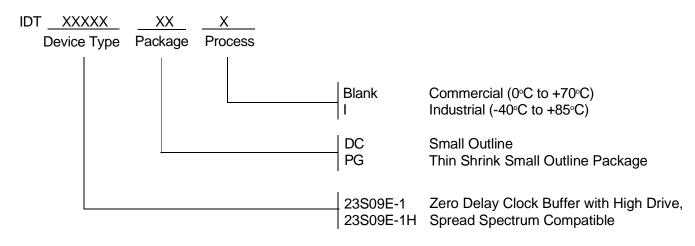


Input to Output Propagation Delay



Device to Device Skew

ORDERING INFORMATION



Ordering Code	PackageType	Operating Range
IDT23S09E-1DC	16-Pin SOIC	Commercial
IDT23S09E-1DCI	16-Pin SOIC	Industrial
IDT23S09E-1HDC ⁽¹⁾	16-Pin SOIC	Commercial
IDT23S09E-1HDCI ⁽¹⁾	16-Pin SOIC	Industrial
IDT23S09E-1HPG ⁽¹⁾	16-Pin TSSOP	Commercial
IDT23S09E-1HPGI ⁽¹⁾	16-Pin TSSOP	Industrial

NOTE:

1. Contact factory for availability.



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